

ABSTRACT

DICING TAPE-COMBINED ADHESIVE SHEET

A dicing tape-combined adhesive sheet includes a dicing tape and a film. The dicing tape includes a radiation-curable pressure-sensitive adhesive layer defining its surface. The film is an adhesive sheet and includes a laser mark layer and an adhesive layer. In the film, the surface defined by the adhesive layer has a peel adhesion strength to a silicon wafer of 5 N/10 mm or more in a peel test under specific conditions. The first peel adhesion strength between the pressure-sensitive adhesive layer after curing and the film is 0.15 N/20 mm or less in a peel test under the conditions. The difference between a second peel adhesion strength and the first peel adhesion strength is 0.12 N/20 mm or less, where the second peel adhesion strength is determined, after storage at 50°C for 9 days, between the pressure-sensitive adhesive layer after curing and the film in a peel test under the conditions. The dicing tape-combined adhesive sheet according to the present invention is suitable for actually providing satisfactory pick-up of adhesive film-bearing semiconductor chips from the dicing tape.

Fig. 1